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# Integrated internal ion-gated organic electrochemical transistors for stand-alone conformable bioelectronics

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# Integrated internal ion-gated organic electrochemical transistors for stand-alone conformable bioelectronics

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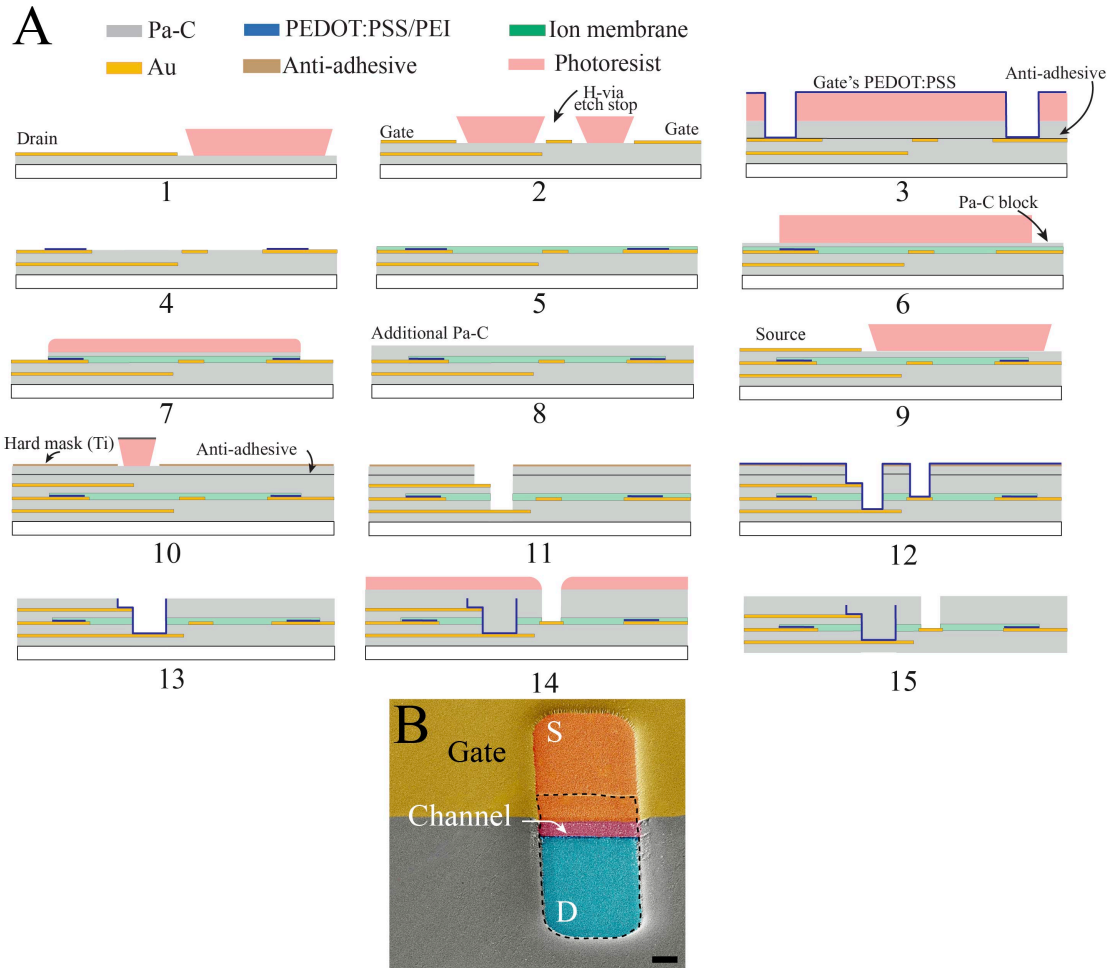
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## Abstract

Organic electronics can be biocompatible and conformable, enhancing the ability to interface with tissue. However, limitations of speed and integration have thus far necessitated reliance on silicon-based technologies for advanced processing, data transmission, and device powering. Here, we create a stand-alone, conformable, fully organic bioelectronic device capable of realizing these functions. This device is based on a novel transistor architecture that incorporates a vertical channel and miniaturized hydration access conduit to enable MHz signal range operation within densely packed integrated arrays in the absence of crosstalk (vertical internal ion-gated organic electrochemical transistor, vIGT). vIGTs demonstrated long-term stability in physiologic media, and were used to generate high performance integrated circuits. We leveraged the high speed and low voltage operation of vIGTs to develop alternating current-powered conformable circuitry to acquire and wirelessly communicate signals. The resultant stand-alone device was implanted in freely moving rodents to acquire, process, and transmit neurophysiologic brain signals. Such fully organic devices have the potential to expand the utility and accessibility of bioelectronics to a wide range of clinical and societal applications.

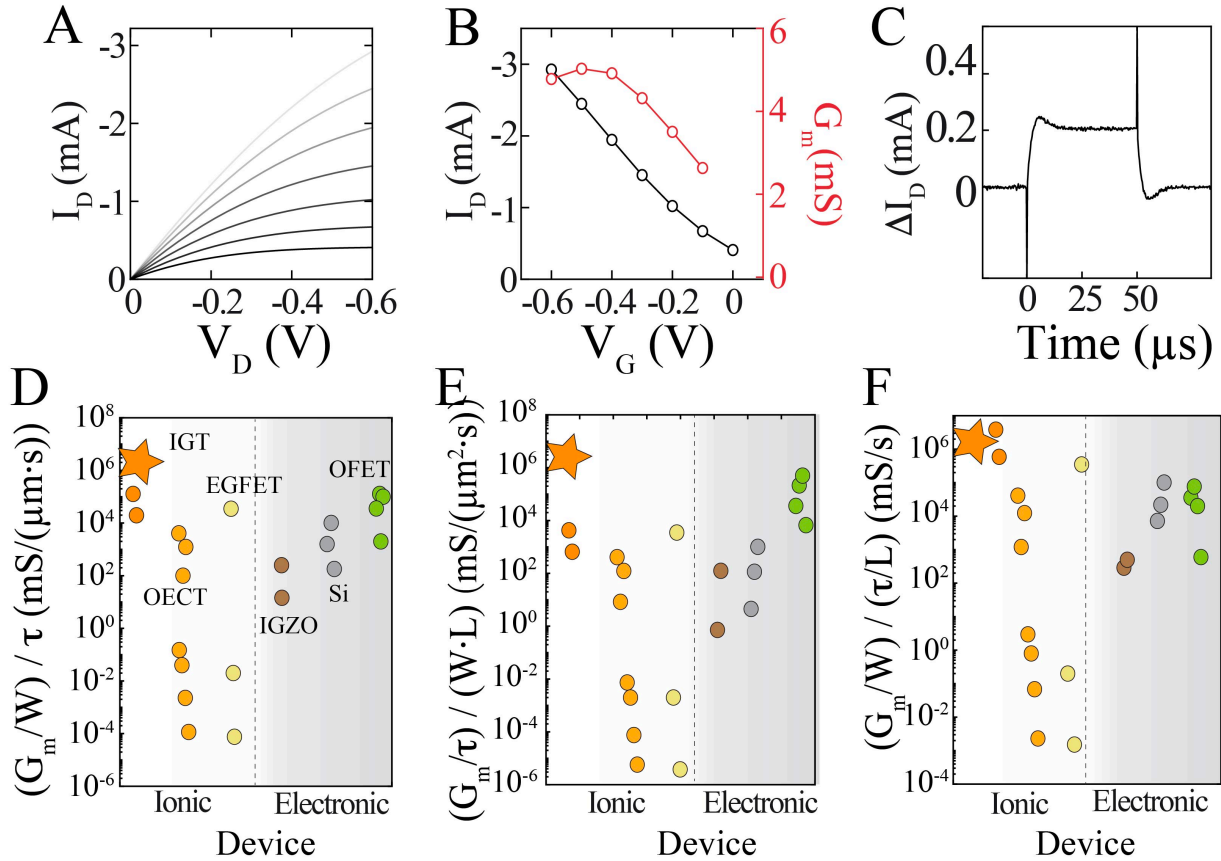


**Supplementary Figure 1: vIGT microfabrication process and SEM images.**

A) Optical lithography-based microfabrication process of sub-micrometer vIGTs.

1. Patterning of drain electrodes (Au/Ti;150/15 nm) via photolithography and lift-off process.
2. Deposition of Pa-C layer (300 nm) and patterning of the second metal layer serving as gate electrode, same parameters as 1.
3. Peel-off process for gate PEDOT:PSS patterning performed by lithography and O<sub>2</sub> plasma etching.
4. Finalized metal 2 layer with interconnects and gate electrodes coated with PEDOT:PSS.
5. Deposition of ion membrane (IM) layer by spin coating (purified chitosan: 250 nm).
6. Protection of IM by a thin Pa-C (<150 nm) layer and photolithographic patterning of the IM area.
7. O<sub>2</sub> plasma etching (180 W) of IM. A mild, 1-3 sccm CH<sub>4</sub>/SF<sub>6</sub> mixture was used for removal of SiO<sub>2</sub> originating from the silane-based Pa-C adhesion promoter.
8. Addition of Pa-C layer to cover the unintended etch areas during IM plasma etch.
9. Patterning of source electrodes (Au/Ti;150/15 nm) via photolithography and lift-off process.
10. Deposition of Ti-based hard etch mask for defining the channel area on top of a peelable sacrificial Pa-C layer.
11. O<sub>2</sub> plasma etching (180 W) of IM (same as 5); Au source and drain contacts act as etch stops.
12. Deposition of the conducting polymer channel using spin coating.
13. Peel-off process of the sacrificial Pa-C layer made possible because of anti-adhesive treatment.
14. Photolithographic patterning and O<sub>2</sub> plasma etching of the H-via.
- 15) Final transistor architecture.

B) Top view SEM (30° tilt) of an individual vIGT channel during fabrication prior to PEDOT:PSS deposition (scale bar, 5 μm). The gate metal interlayer is represented by the yellow shaded region.



**Supplementary Figure 2: Output characteristics ( $I_D$ - $V_D$ ) and temporal response of an enhancement mode vIGT.**

A) Output characteristics ( $I_D$ - $V_D$ ) of an enhancement mode vIGT ( $L = 1 \mu\text{m}$ ,  $W = 5 \mu\text{m}$ , thickness of PEDOT:PSS = 100 nm) for  $V_G$  varying from 0 V (bottom curve) to -0.6 V (top curve) with a step of 0.1 V; color intensity corresponds to  $V_G$  amplitude (left). Transfer curve for  $V_D = -0.6$  V (black) with corresponding transconductance (red),  $G_m = 5.03$  mS (right). Star represents vIGT.

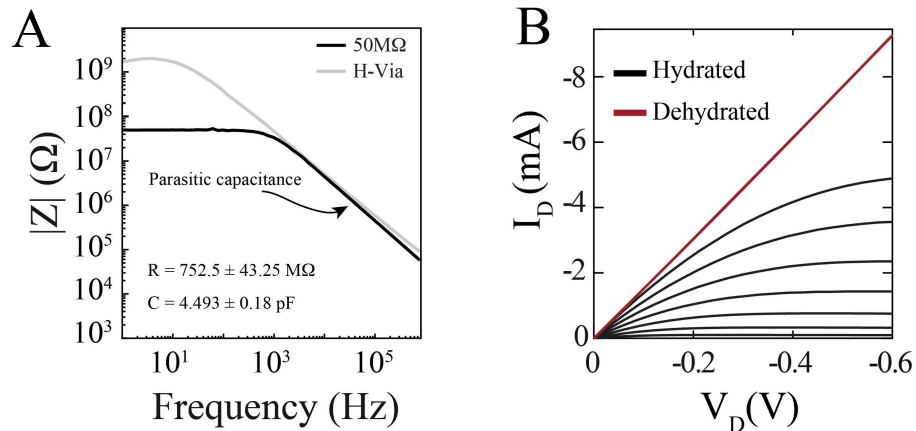
B) Corresponding temporal response of the drain current ( $I_D$ ) for  $V_D = -0.6$  V and  $V_G$  pulse amplitude of 0.1 V.

C) Exponential fit of the vIGT drain current resulted in a time constant of 0.8  $\mu$ s (right).

D) Expanded version of **Figure 1G**.

E) Performance of flexible transistors as characterized by the normalized ratio of transconductance and rise time vs. channel area. Same color scheme as **Figure 1G**.

F) Performance of flexible transistors as characterized by the ratio of the normalized transconductance by width and normalized rise time by channel length. Same color scheme as **Figure 1G**.

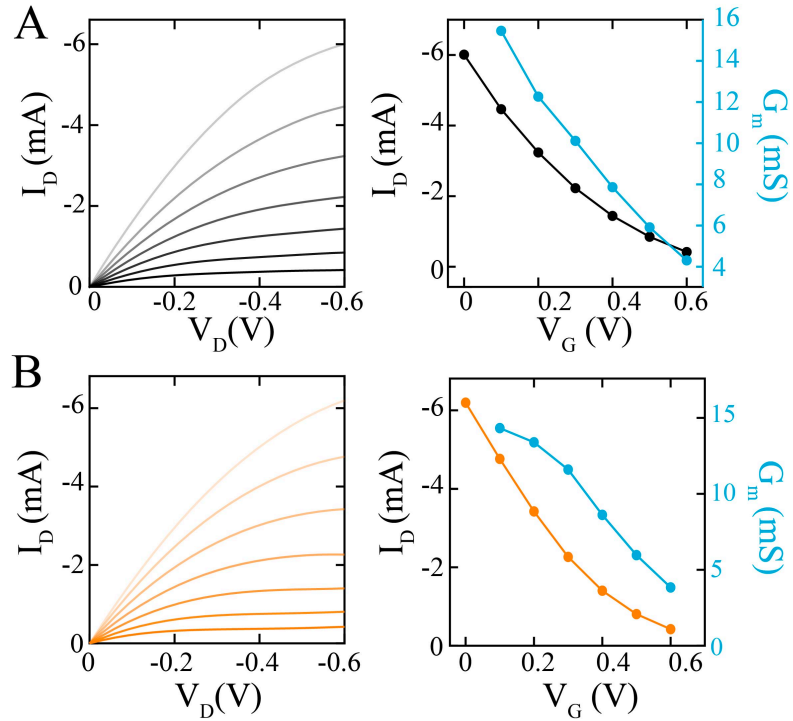


**Supplementary Figure 3: Electrochemical impedance characterization of vIGT and H-via.**

A) 4-electrode potentiostatic mode EIS on a ceramic-based 50 M $\Omega$  resistor (black). The EIS contains a capacitive component that is attributed to the instrument and setup parasitic capacitance. An RC model was used to extract this capacitance ( $\sim 4.5$  pF).

To measure the impedance of the H-via in a 4-electrode setting, we fabricated vIGTs without the conducting polymer channel connecting source and drain contacts. This set-up allowed utilization of source and drain contacts as 2 separate electrodes below the H-via, while a pair of Ag/AgCl and Pt wires served as the remaining electrodes above the H-via. The EIS measurement of the H-via was then compared to the pure resistor calibration measurements. The EIS fitting of the H-via curve had a capacitance value consistent with the parasitic capacitance extracted during the pure resistor measurements.

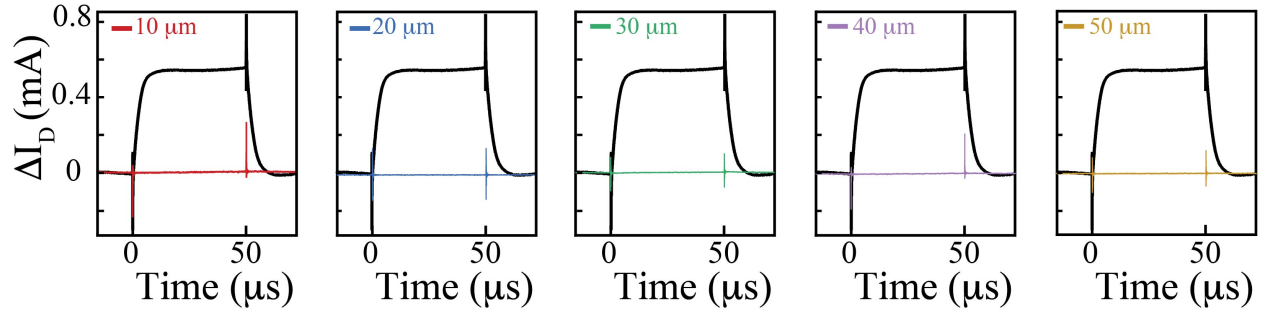
B) Comparison of output characteristics of a dehydrated channel (red) vs. a channel hydrated through the H-via (black).



**Supplementary Figure 4: H-via does not impede vIGT electrical performance.**

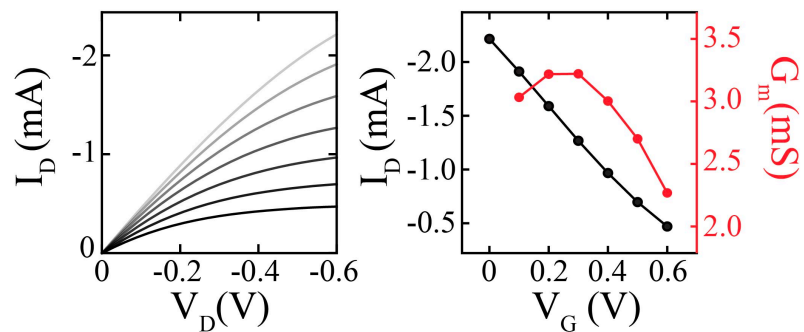
A) Corresponding output characteristics ( $I_D$ - $V_D$ ) of the vIGT with channel fully exposed to electrolyte shown as the black curve in **Figure 2B**.  $V_G$  varies from 0 V (top curve) to 0.6 V (bottom curve) with a step of 0.1 V; color intensity corresponds to  $V_G$  amplitude (left). Transfer curve for  $V_D = -0.6$  V (black) with corresponding transconductance (blue),  $G_m^{\max} = 15.45$  mS (right).

B) Corresponding output characteristics ( $I_D$ - $V_D$ ) of the vIGT with H-via exposure shown as the orange curve in **Figure 2B**.  $V_G$  varies from 0 V (top curve) to 0.6 V (bottom curve) with a step of 0.1 V; color intensity corresponds to  $V_G$  amplitude (left). Transfer curve for  $V_D = -0.6$  V (orange) with corresponding transconductance (blue),  $G_m^{\max} = 14.33$  mS (right).



**Supplementary Figure 5: H-via enables creation of densely packed, independently-addressable vIGTs without inter-transistor crosstalk.**

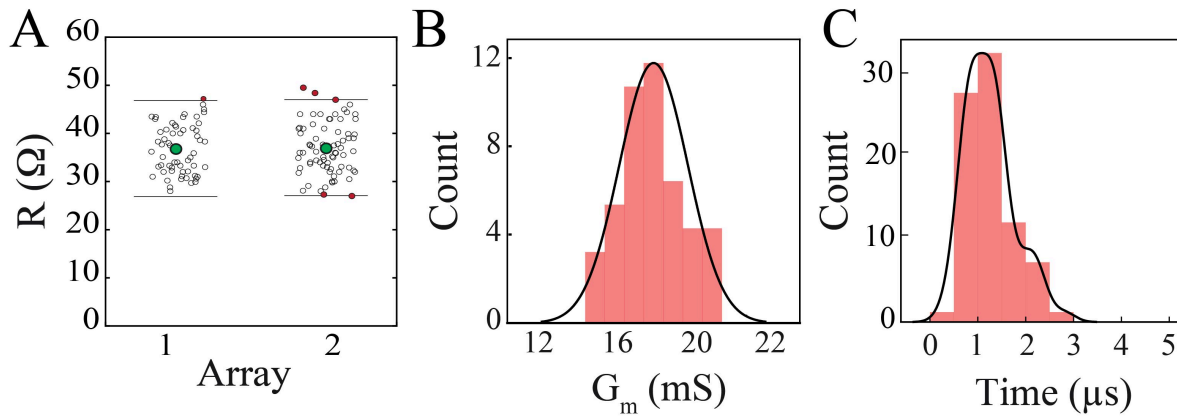
Corresponding temporal responses of the drain current ( $I_D$ ) of the vIGT shown in **Figure 2F** with input applied to its own gate (black curves) vs. input applied to neighboring transistor gates at channel-to-gate distances varying from 10  $\mu\text{m}$  to 50  $\mu\text{m}$  (colored curves). Transistor was operated at  $V_D = -0.4$  V, with pulsed  $V_G$  between 0 - 0.6 V ( $n = 128$  pulses per current measurement). Transistors had identical geometry ( $W/L = 5/0.8$   $\mu\text{m}$ ,  $d = 100$  nm).



**Supplementary Figure 6: vIGT performance exhibits long-term stability in physiologic conditions.**

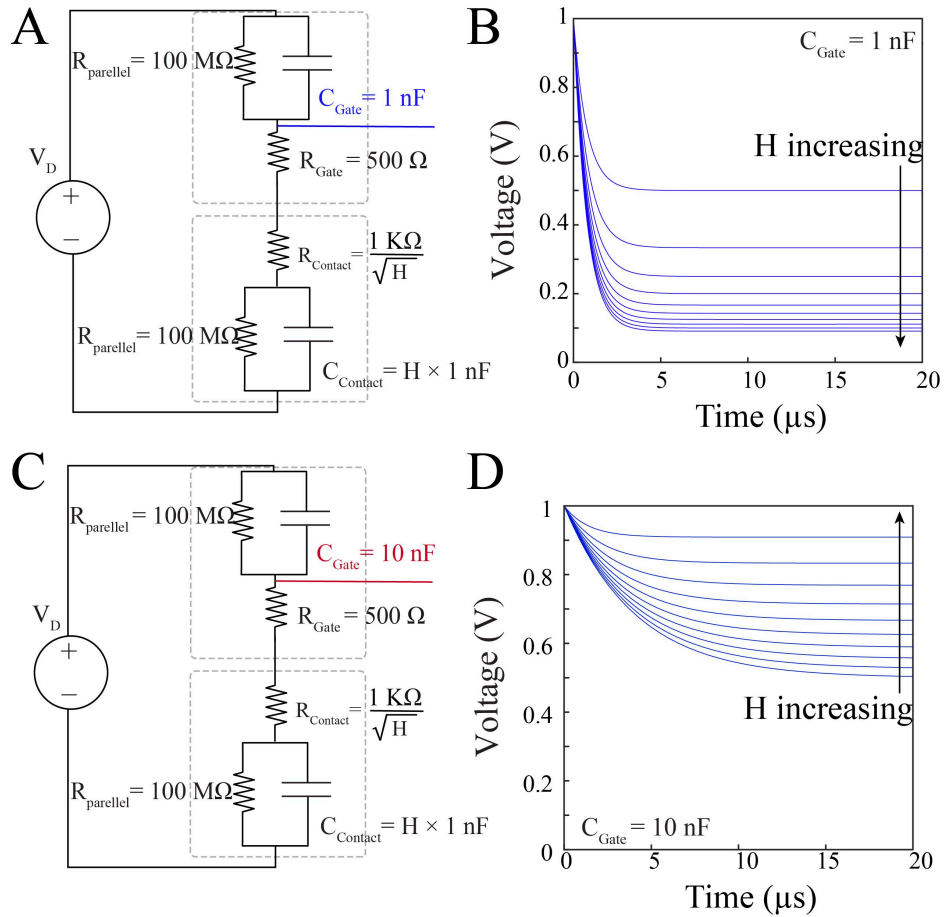
Output characteristics ( $I_D$ - $V_D$ ) of the vIGT shown in **Figure 1E** after 362 days in PBS solution.  $V_G$  varies from 0 V (top curve) to 0.6 V (bottom curve) with a step of 0.1 V; color intensity corresponds to  $V_G$  amplitude (left). Transfer curve for  $V_D = -0.6$  V (black) with corresponding transconductance (red),  $G_m^{\max} = 3.22$  mS (right).





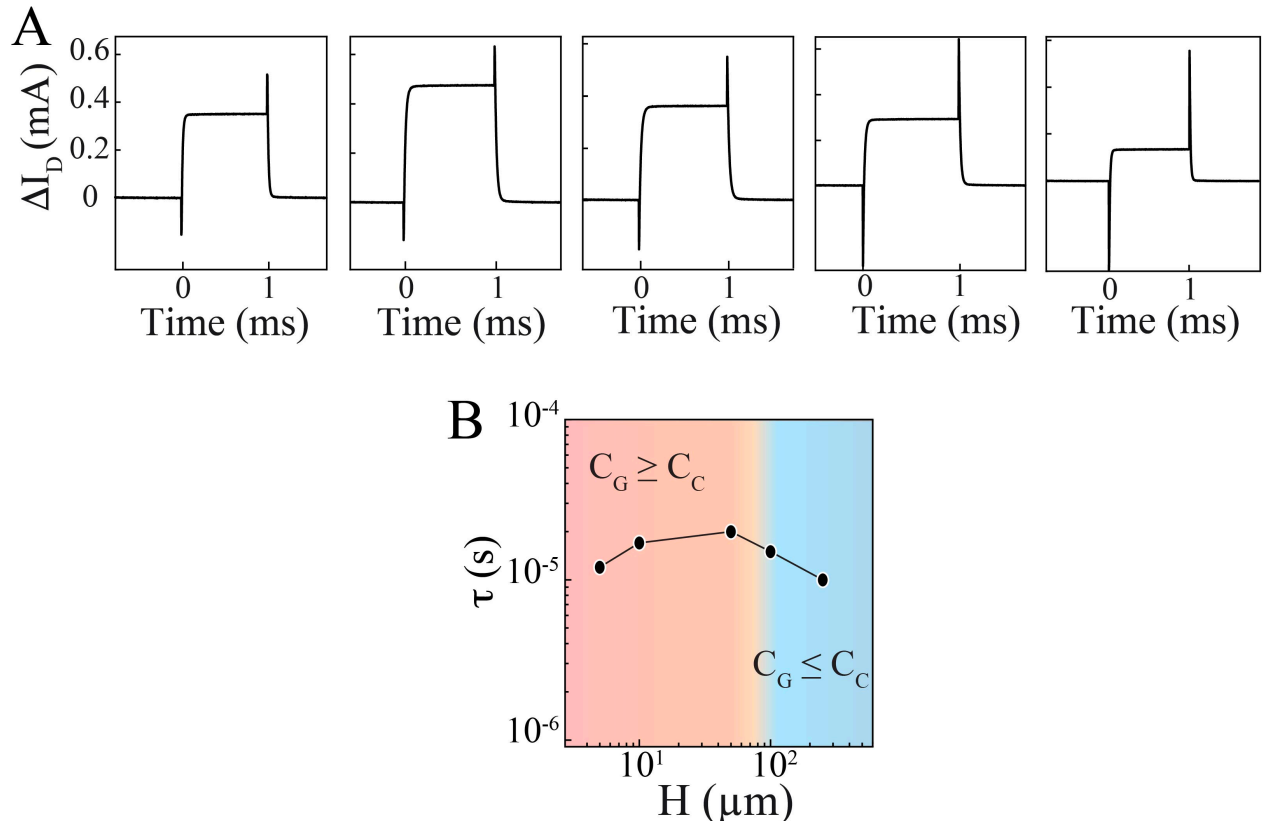
**Supplementary Figure 7: Wafer-scale fabrication of vIGTs with consistent performance.**

A) Distribution of the channel resistances of two independent arrays of transistors. The black lines demarcate the acceptable variation in resistance ( $1 \times \text{std}$ ). Green filled symbols mark the mean and the red circles highlight the rejected transistors ( $n = 138$  total devices with 6 rejected devices).  
 B) Histogram of the transconductance values for vIGTs ( $W/L = 15/0.8 \mu\text{m}$ ) across multiple wafers. Superimposed black line shows the corresponding fitted distribution.  
 C) Histogram of temporal response values for vIGTs across multiple wafers. Superimposed black line shows the corresponding fitted distribution.



**Supplementary Figure 8: Modeling and equivalent circuit diagrams for gate and contact interactions.**

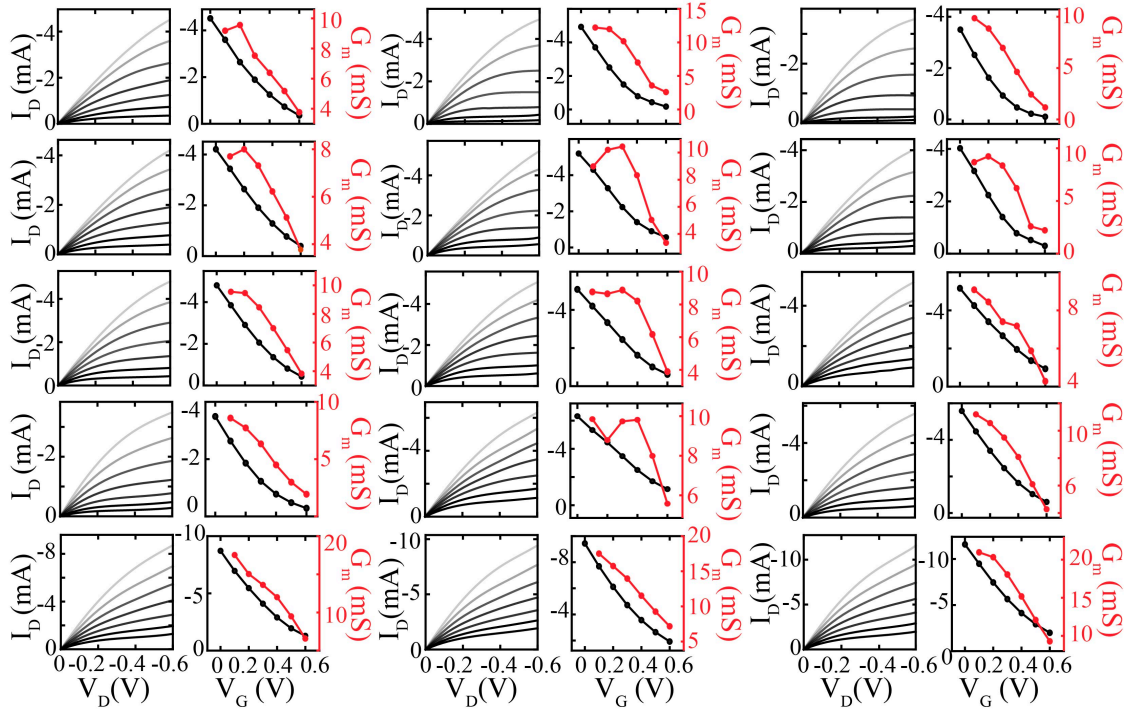
- A) Circuit model of the gate and contact resistance, as well as capacitance, when the gate has a smaller area than the contact.
- B) Simulation output used to measure the time constant as  $H$  (contact length) is increased from 1 to 10 in the gate < contact area condition.
- C) Circuit model of the gate and contact resistance, as well as capacitance, when the gate has a larger area than the contact.
- D) Simulation output used to measure the time constant as  $H$  (contact length) is increased from 1 to 10 in the gate > contact area condition.



**Supplementary Figure 9: Contact area has a non-linear relationship with temporal response.**

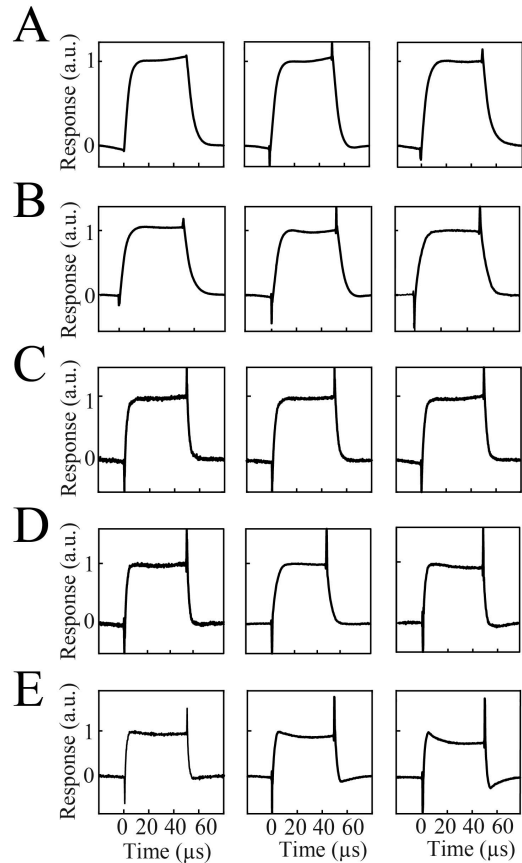
A) Relationship between contact length ( $H$ ) and temporal response for a horizontal channel IGT ( $W/L = 100 / 100 \mu\text{m}$ ). Corresponding temporal response of the vIGTs with  $H = 5, 10, 50, 100, 250 \mu\text{m}$ .

B) Time constant of the horizontal IGT as a function of contact area ( $W/L = 100 / 100 \mu\text{m}$ ).



**Supplementary Figure 10: Effect of contact area on temporal response of vIGT.**

Corresponding output characteristics ( $I_D$ - $V_D$ ) of the vIGT shown in **Figure 3C**. Each row corresponds to five different contact length values (12  $\mu\text{m}$ , 30  $\mu\text{m}$ , 110  $\mu\text{m}$ , 250  $\mu\text{m}$  and 500  $\mu\text{m}$ ). Transistors in the same row have the same geometry for evaluation of consistency ( $n = 3$ ).



**Supplementary Figure 11: vIGTs with larger channel contact length (H) have faster temporal responses.**

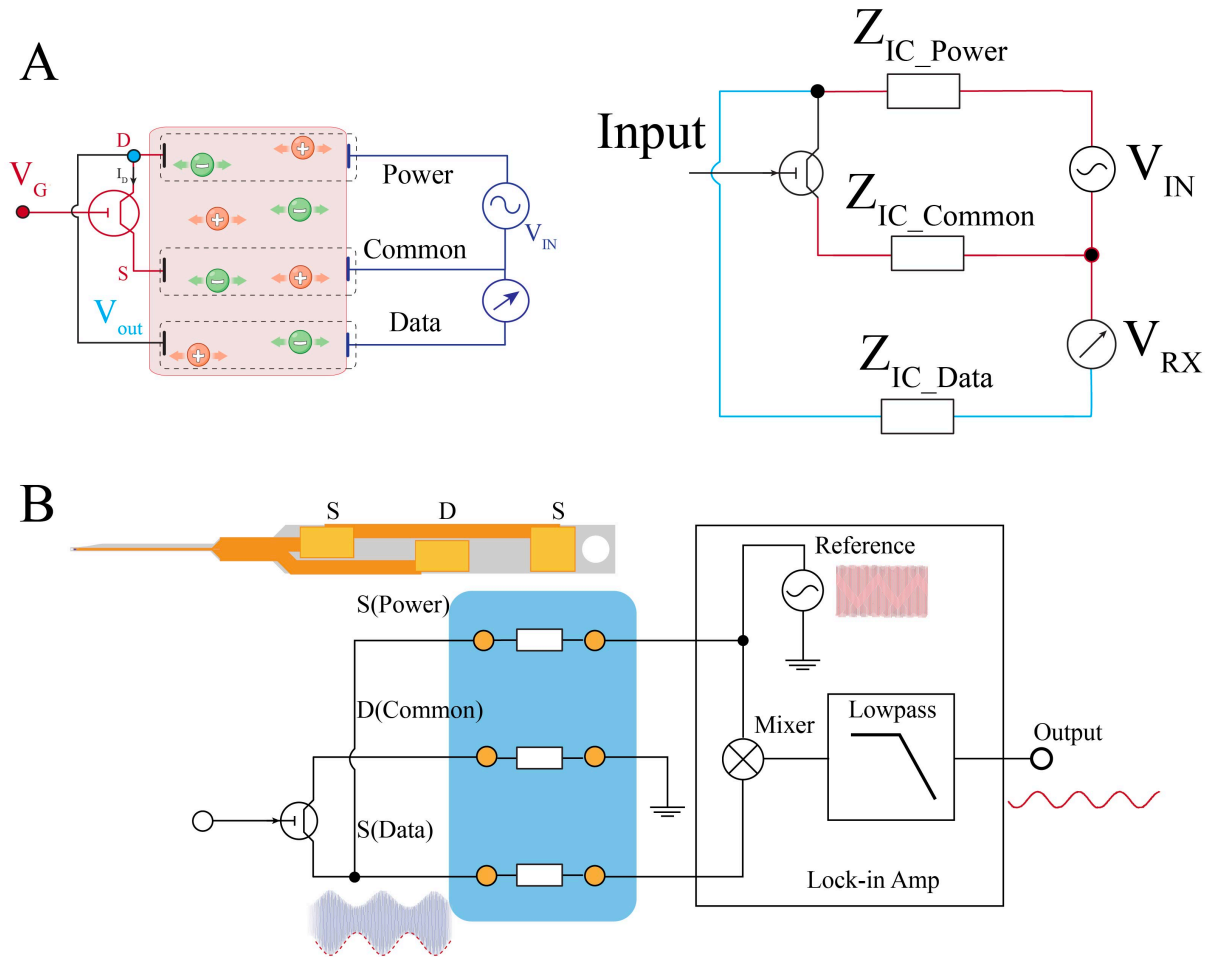
A) Corresponding temporal responses of vIGTs with  $H = 12 \mu\text{m}$  shown in **Figure 3D**,  $\tau = 3.7 \mu\text{s} \pm 0.28 \mu\text{s}$  ( $n = 3$ , mean  $\pm$  standard deviation).

B) Corresponding temporal responses of vIGTs with  $H = 30 \mu\text{m}$  shown in **Figure 3D**,  $\tau = 3.0 \mu\text{s} \pm 0.74 \mu\text{s}$  ( $n = 3$ , mean  $\pm$  standard deviation).

C) Corresponding temporal responses of vIGTs with  $H = 110 \mu\text{m}$  shown in **Figure 3D**,  $\tau = 1.7 \mu\text{s} \pm 0.14 \mu\text{s}$  ( $n = 3$ , mean  $\pm$  standard deviation).

D) Corresponding temporal responses of vIGTs with  $H = 250 \mu\text{m}$  shown in **Figure 3D**,  $\tau = 1.3 \mu\text{s} \pm 0.06 \mu\text{s}$  ( $n = 3$ , mean  $\pm$  standard deviation).

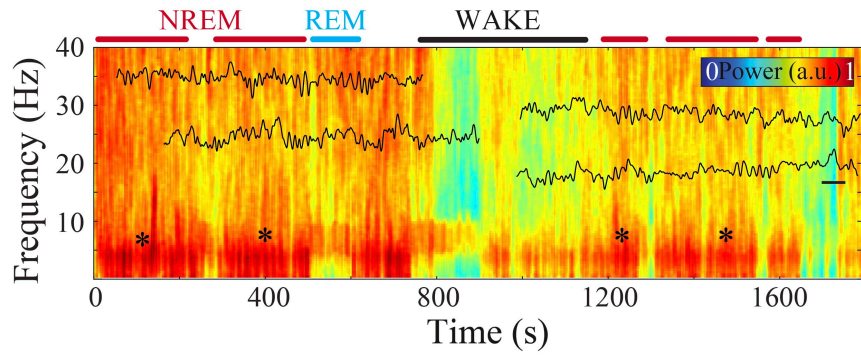
E) Corresponding temporal responses of vIGTs with  $H = 500 \mu\text{m}$  shown in **Figure 3D**,  $\tau = 0.8 \mu\text{s} \pm 0.20 \mu\text{s}$  ( $n = 3$ , mean  $\pm$  standard deviation).



**Supplementary Figure 12: Equivalent circuit diagram of stand-alone vIGT.**

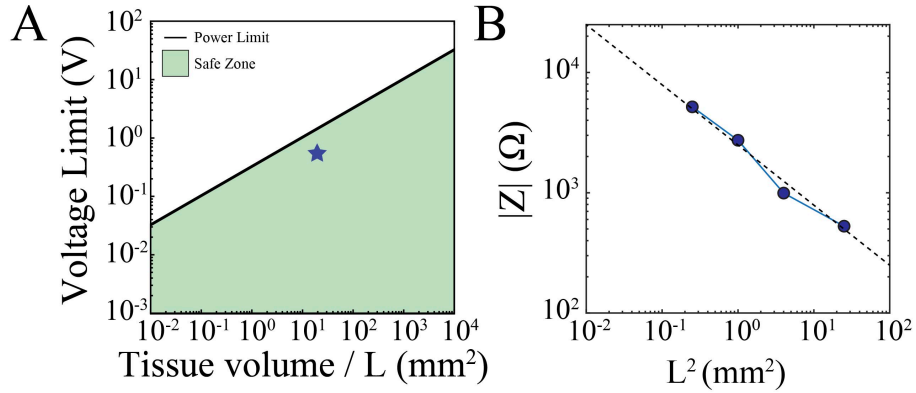
A) Simplified circuit model of the wireless vIGT-based stand-alone device.  $Z_{IC\_Common}$  denotes impedance of grounding IC channel (source electrode).  $Z_{IC\_Power}$  denotes impedance of primary IC channel for power delivery (drain electrode).  $Z_{IC\_Data}$  denotes impedance of secondary IC channel for signal output.

B) Top view schematic of the vIGT-based wireless probe and the block diagram of the receiver.



**Supplementary Figure 13: Neurophysiological data acquired and transmitted by stand-alone vIGT device *in vivo*.**

Continuous time-frequency spectrogram of neural data acquired and wirelessly transmitted using vIGT-based stand-alone device demonstrates characteristic LFP patterns corresponding to wakefulness, REM sleep, and NREM sleep. Superimposed raw time trace highlights spindle oscillations during NREM sleep (scale bar, 200 ms).



**Supplementary Figure 14: Stand-alone vIGT-based wireless implant complies with safety values for tissue specific energy absorption rate (SAR) as mandated by the International Commission on Non-Ionizing Radiation Protection (ICNIRP).**

A) Operating voltage limit of the stand-alone vIGT-based wireless implant as a function of the tissue volume between its electrodes and the size of the electrode ( $L$ ). The black line indicates the safety boundary for the induced electric field in the tissue. The green shaded area highlights the compliant voltages for a given configuration. The star indicates the parameters used in our *in vivo* studies ( $V_{TX} = 500$  mV,  $L = 1$  mm).

B) Measured (blue circles) and fitted (dashed line) impedance values as a function of electrode area ( $L^2$ ) used for estimation of operating voltages.



Device	$\tau$ (s)	$G_m^{\max}$ (mS)	$(G_m^{\max}/W)/\tau$ (mS/ $\mu\text{m s}$ )	L ( $\mu\text{m}$ )	W ( $\mu\text{m}$ )
V-IGT	$9.20 \times 10^{-7}$	$3.87 \times 10^0$	$2.10 \times 10^6$	$8.00 \times 10^{-1}$	$2.00 \times 10^0$
E-IGT <sup>16</sup>	$8.60 \times 10^{-6}$	$5.49 \times 10^0$	$1.28 \times 10^5$	$3.00 \times 10^1$	$5.00 \times 10^0$
DIGT <sup>15</sup>	$2.80 \times 10^{-5}$	$6.62 \times 10^0$	$1.97 \times 10^4$	$3.00 \times 10^1$	$1.20 \times 10^1$
DOECT <sup>39,51</sup>	$3.90 \times 10^{-5}$	$1.60 \times 10^0$	$4.10 \times 10^3$	$1.00 \times 10^1$	$1.00 \times 10^1$
E-OECT <sup>16</sup>	$2.29 \times 10^{-4}$	$5.74 \times 10^0$	$1.00 \times 10^2$	$1.20 \times 10^1$	$2.50 \times 10^2$
g2T-T <sup>52</sup>	$6.40 \times 10^{-4}$	$7.90 \times 10^0$	$1.23 \times 10^3$	$1.00 \times 10^1$	$1.00 \times 10^1$
PTEBS:PEDOTS	$7.10 \times 10^{-2}$	$1.19 \times 10^1$	$1.49 \times 10^{-2}$	$2.00 \times 10^1$	$1.125 \times 10^3$
S-aPEDOT <sup>53</sup>	$3.60 \times 10^{-1}$	$1.62 \times 10^1$	$4.00 \times 10^{-2}$	$2.00 \times 10^1$	$1.125 \times 10^3$
ZnO <sub>2</sub> <sup>36</sup>	$5.00 \times 10^{-7}$	$3.5 \times 10^0$	$3.50 \times 10^4$	$10 \times 10^0$	$200 \times 10^0$
ZnO <sub>2</sub> <sup>54</sup>	$5.00 \times 10^{-5}$	$2.00 \times 10^{-4}$	$2.00 \times 10^{-2}$	$1.00 \times 10^1$	$2.00 \times 10^2$
BBL:PEI <sup>55</sup>	$1.67 \times 10^{-1}$	$3.80 \times 10^{-1}$	$2.28 \times 10^{-3}$	$3.00 \times 10^1$	$1.00 \times 10^3$
PTEBS <sup>53</sup>	$6.90 \times 10^0$	$9.00 \times 10^{-1}$	$1.16 \times 10^{-4}$	$2.00 \times 10^1$	$1.125 \times 10^3$
P3HT <sup>56</sup>	$1.00 \times 10^{-3}$	$1.52 \times 10^{-5}$	$7.60 \times 10^{-5}$	$2.00 \times 10^1$	$2.00 \times 10^2$
Si NM <sup>57</sup>	$1.50 \times 10^{-6}$	$5.00 \times 10^{-1}$	$1.01 \times 10^4$	$1.00 \times 10^1$	$3.30 \times 10^1$
V-OFET <sup>58</sup>	$1.00 \times 10^{-7}$	$1.00 \times 10^{-3}$	$2.00 \times 10^3$	$3.00 \times 10^{-1}$	$5.00 \times 10^0$
OEFT <sup>59</sup>	$5.6 \times 10^{-7}$	$8.00 \times 10^{-3}$	$1.78 \times 10^2$	$1.20 \times 10^{-1}$	$80 \times 10^0$
OEFT <sup>60</sup>	$5.60 \times 10^{-8}$	$4.00 \times 10^{-1}$	$3.57 \times 10^4$	$1.00 \times 10^0$	$200 \times 10^0$
OEFT <sup>60</sup>	$4.70 \times 10^{-8}$	$6.00 \times 10^{-1}$	$1.28 \times 10^5$	$6.00 \times 10^{-1}$	$100 \times 10^0$
OEFT <sup>61</sup>	$4.00 \times 10^{-8}$	$2.00 \times 10^{-1}$	$1.00 \times 10^5$	$2.00 \times 10^{-1}$	$50 \times 10^0$
Si NM <sup>62</sup>	$5.00 \times 10^{-6}$	$1.80 \times 10^{-1}$	$1.80 \times 10^2$	$4.00 \times 10^1$	$2.00 \times 10^2$
Si NM <sup>63</sup>	$2.60 \times 10^{-6}$	$3.30 \times 10^{-1}$	$1.59 \times 10^3$	$1.38 \times 10^1$	$8.00 \times 10^1$
IGZO <sup>64</sup>	$6.92 \times 10^{-8}$	$1.00 \times 10^{-4}$	$1.45 \times 10^1$	$2.00 \times 10^1$	$1.00 \times 10^2$
IGZO <sup>65</sup>	$1.00 \times 10^{-5}$	$3.00 \times 10^0$	$2.50 \times 10^2$	$2.00 \times 10^0$	$1.2 \times 10^3$

**Supplementary Table 1: Electrical and geometrical characteristics of flexible transistors shown in Figure 1E.**

Material	Density (transistors/cm <sup>2</sup> )
Si NMOS <sup>66</sup>	$2.424 \times 10^3$
Si NM <sup>57</sup>	$9.090 \times 10^3$
EGOFET ZnO <sup>54</sup>	$2.0 \times 10^2$
IGZO TFTs <sup>67</sup>	$9.5169 \times 10^4$
C-OTFT <sup>68</sup>	$6.0 \times 10^1$
OECT <sup>69</sup>	$1.0 \times 10^2$
OECT <sup>70</sup>	$3.25 \times 10^2$
CNT FET <sup>71</sup>	$4.0 \times 10^3$
OTFT <sup>72</sup>	$6.25 \times 10^3$
gSGFET <sup>73-75</sup>	$1.111 \times 10^3$
OFET <sup>76</sup>	$4.2 \times 10^4$
VIGT	$1.55586 \times 10^5$
OECT <sup>77</sup>	$3.1746 \times 10^4$
OECT-OFET <sup>78</sup>	25

**Supplementary Table 2: Density of flexible transistors shown in Figure 4C.**

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